

D446-VB Datasheet N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
100	0.114 at V _{GS} = 10 V	15			

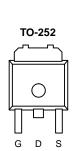
FEATURES

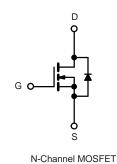
- Trench Power MOSFET
- 150 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

· Primary Side Switch





ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V		
Gate-Source Voltage		V_{GS}	± 20			
Continuous Drain Current (T _{.I} = 175 °C) ^b	T _C = 25 °C	I _D	15			
Continuous Diam Current (1j = 175 C)	T _C = 125 °C	טי	13			
Pulsed Drain Current		I _{DM}	40	A		
Continuous Source Current (Diode Conduction)		I _S	3			
Avalanche Current	I _{AS}	3				
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	18	mJ		
Maximum Power Dissipation	T _C = 25 °C	P _D	96 ^b	W		
Maximum Fower Dissipation	T _A = 25 °C	' D	3 ^a]		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
hunding to Ambient	t ≤ 10 s	- R _{thJA}	15	18	°C/W	
Junction-to-Ambient ^a	Steady State		40	50		
Junction-to-Case (Drain)	•	R _{thJC}	0.85	1.1		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.



Parameter	Symbol	Test Conditions Min.		Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$ $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$				V
Gate Threshold Voltage	V _{GS(th)}				3.5	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V _{DS} = 100 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I_{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C		250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			Α
		$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.114		
Danie Course On State Besistance	R	V _{GS} = 10 V, I _D = 3 A, T _J = 125 °C		0.120		0
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C		0.140		Ω
		$V_{GS} = 4.5 \text{ V } I_D = 3 \text{ A}$		0.120		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		35		S
Dynamic ^a						
Input Capacitance	C_{iss}			950		
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, F = 1 \text{ MHz}$		120		pF
Reverse Transfer Capacitance	C _{rss}			60		
Total Gate Charge ^c	Q_g			24	41	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		8		nC
Gate-Drain Charge ^c	Q_{gd}			12		
Gate Resistance	R_g		0.5		2.9	Ω
Turn-On Delay Time ^c	t _{d(on)}			15	25	
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 5.2 \Omega$		50	75	nc
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	ns
Fall Time ^c	t _f			60	90	
Source-Drain Diode Ratings and Char	acteristics (7	T _C = 25 °C)				
Pulsed Current	I _{SM}				5	Α
Diode Forward Voltage ^b	V_{SD}	I _F = 3 A, V _{GS} = 0 V		0.9	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3 A, dI/dt = 100 A/μs		180	250	ns

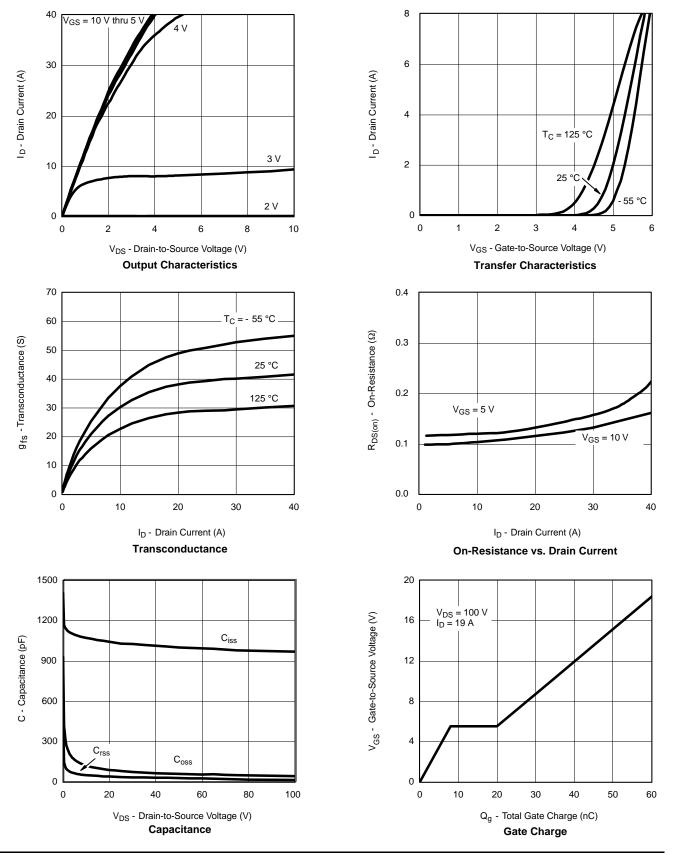
Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

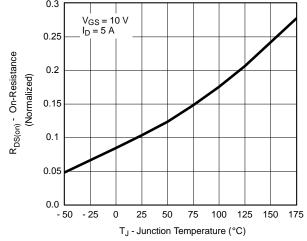


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

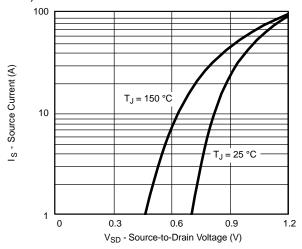




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature

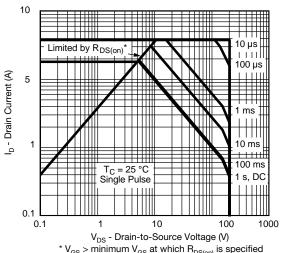


Source-Drain Diode Forward Voltage

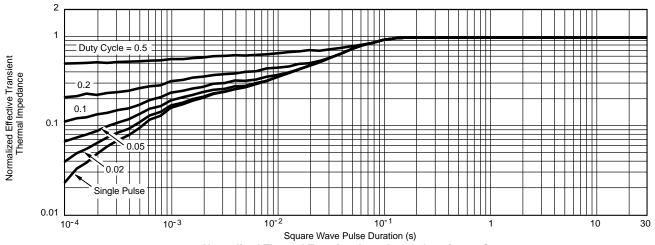
THERMAL RATINGS



Maximum Avalanche Drain Current vs. Case Temperature



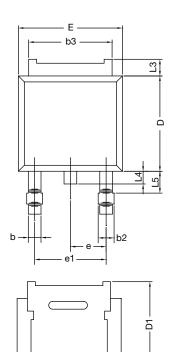
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified **Safe Operating Area**

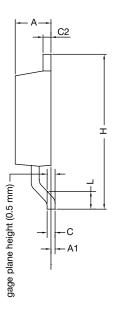


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE





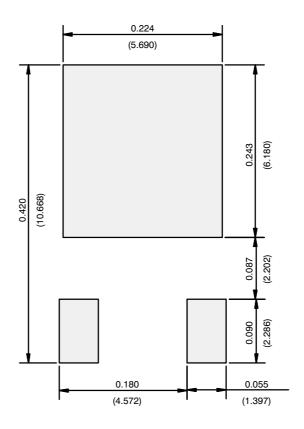
	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	=	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	=	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	2.28 BSC		BSC	
e1	4.56	4.56 BSC		BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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